

APPROVAL SHEET

To :

Customer P/N :

UDE P/N : SS10-ZZ-0008

Description : SFP+ Cage 1X1

DIP

Without Lightpipe&heatsink

Packing With Hard Tray



Spec No.
SS1020021-00

Update Date
2020/5/4

Revision
A

Approved	Checked	Prepared



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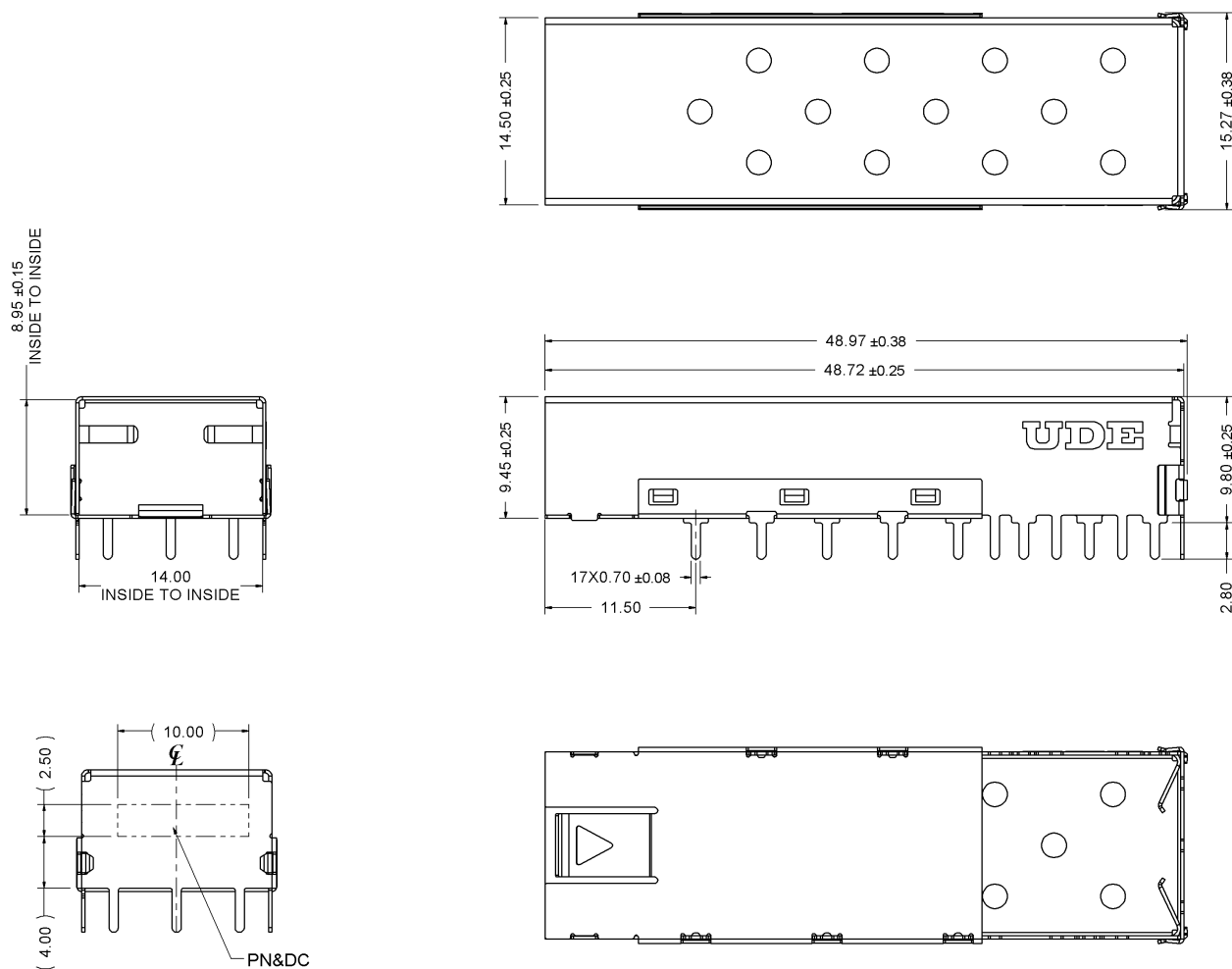
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1. MECHANICAL DIMENSION

1.1 CAGE assembly Dimension

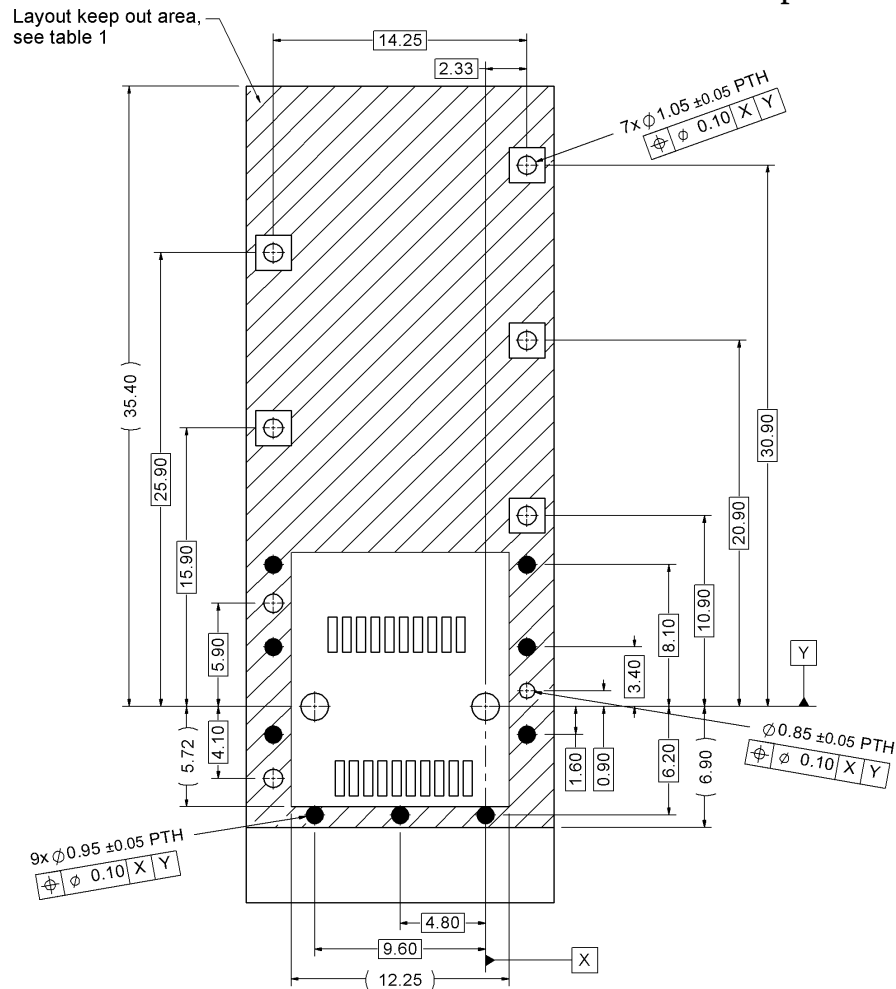
General Tolerance : X.X : ± 0.38
X.XX : ± 0.20



1.2 Recommended PCB Layout

Component Side of Board

All dimension tolerances are $\pm 0.05\text{mm}$ unless otherwise specified



NOTES:

1.PADS AND VIAS CONNECT TO CHASSIS GROUND

RECOMMEND PADS TO BE 2.00mm SQUARE

2.RECOMMENDED THRU HOLE PLATING INCLUDES

HASL,OSP,OR IMMERSION(GOLD,SILVER,OR TIN)

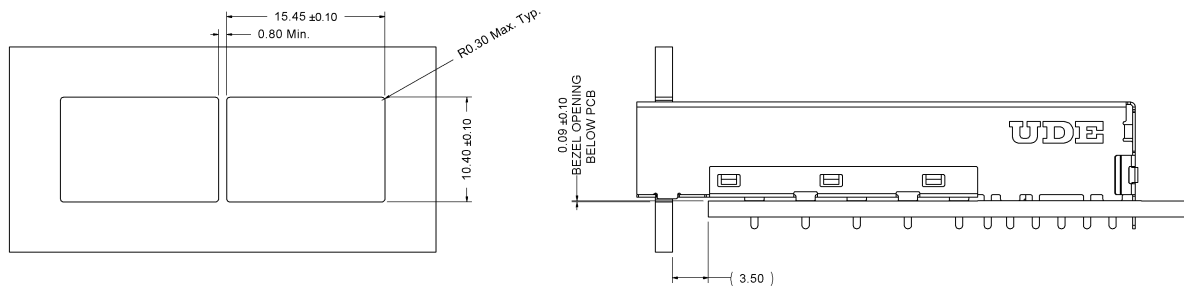
3.1.57mm MINIMUM PCB THICKNESS FOR SINGLE SIDED USE.

Table1

Layout Layer	Trace	component	Grounding	Test Point	Via Hole	PTH	NPTH
Component side	X	X	O	X	X	X	O
Inner layer	O	NA	O	NA	O	X	O
Bottom side	O	O	O	O	O	X	O

X--Forbid; O--OK; NA--Not Applicable.

1.3 Recommended Panel Cutout



1.4 Packing Information

35 pcs finished goods per tray

9 trays(280 pcs finished goods) per master carton

2. REQUIREMENTS

2.1 Design and Construction

Product shall be of design, construction and physical dimensions specified on applicable.

2.2 Material

2.2.1 Shield Parts

2.2.1.1 Top Shell : Copper Alloy, Thickness=0.25mm

2.2.1.2 Bottom Shell : Copper Alloy, Thickness=0.25mm

2.3 Operating and Storage Temperature

Operating Temperature : -40°C to $+85^{\circ}\text{C}$

Storage Temperature : -55°C to $+105^{\circ}\text{C}$

2.4 SFP CAGE specifications

Insertion force : 18 N max at a max. rate of 25.4mm per minute

(SFP module to SFP cage)

Extraction force : 12.5 N max at a max. rate of 25.4mm per minute

(SFP module to SFP cage)

Cage Retention (Latch strength) : 90N Min.

Durability : 100 cycles for standard class

2.5 Performance and Test Description

Product is designed to meet electrical, mechanical and environmental performance requirements specified in below table. All tests are performed at ambient environmental conditions per MIL-STD-1344A and EIA-364 unless otherwise specified.

2.6 Packaging and Packing

All parts shall be packaged and packed to protect against physical damage, corrosion and deterioration during shipment and storage.

3. WAVE SOLDERING TEMPERATURE PROFILE

Note :

The measuring point for the specified temperature shall be on the soldered part of the lead.

